500V N-Channel MOSFET
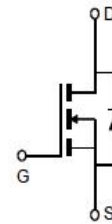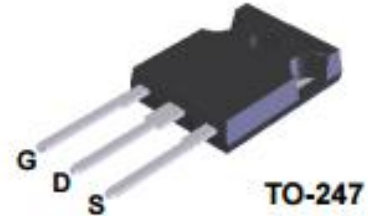
◼ Features

- V_{DSS}=500V I_D=25A
$R_{DS(ON)}$=0.21Ω(Typ.)@V_{GS}=10V,I_D=12.5V
- Low On-Resistance
- Improved dv/dt capability
- Super Low Gate Charge
- 100% EAS Guaranteed
- Green Device Available
- Fast switching speed

◼ Applications

- High frequency switching mode power supply
- Uninterruptible Power Supply (UPS)
- Power Factor Correction (PFC)

◼ PIN DESCRIPTION

Part Number	Package	Marking	ROHS Status	Packing
SI25N50AH	TO-247	SI25N50AH	Pd-Free	Box(Tube)

◼ Absolute Maximum Ratings (Tc=25℃ unless otherwise noted)

Symbol	Parameter		Value	Unit
V_{DS}	Drain-Source Voltage		500	V
V_{GS}	Gate-Source Voltage		±30	V
I_D	Continuous Drain Current	Tc=25℃	25	A
		Tc=100℃	18	A
I_{DM}	Pulsed Drain Current		88	A
E_{AS}	Single Pulse Avalanche Energy		1400	mJ
T_J, T_{stg}	Operating Junction and Storage Temperature Range		-55 to 150	℃
P_D	Total Power Dissipation	Tc=25°C	50	W

◼ THERMAL RESISTANCE RATINGS

Symbol	Paramete	Typical	Max	Unit
$R_{θJA}$	Maximum Junction-to-Ambient	-	65	℃/W
$R_{θJC}$	Maximum Junction-to-Case	-	3.2	

■ Electrical Characteristics (T_C=25℃ unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	TYP.	Max.	Unit
Static Characteristics						
$V_{(BRV)DSS}$	Drain-source breakdown voltage	V_{GS}=0V,I_D= 250uA	500	-	-	V
$V_{GS(th)}$	Gate threshold voltage	V_{DS}=V_{GS},I_D=250uA	3	-	4	V
I_{DSS}	Drain-Source Leakage Current	V_{DS}=500V,V_{GS}=0V	-	-	1	uA
		V_{DS}=400V,V_{GS}=0V,	-	-	10	uA
I_{GSS}	Gate-source leakage current	V_{DS}=0V,V_{GS}=±30V	-	-	±100	nA
$R_{DS(on)}$	Drain-source on-state resistance	V_{GS}=10V,I_D=12.5A	-	0.21	0.26	Ω
g_{FS}	Forward Transconductance	V_{DS}=30V,I_D=5.5A	-	25	-	S
Dynamic Characteristic						
Q_g	Total Gate Charge	V_{GS}=10V,V_{DD}=400V I_D=25A	-	69	-	nC
Q_{gs}	Gate-Source Charge		-	22	-	nC
Q_{gd}	Gate-Drain Charge		-	24	-	nC
$T_{d(on)}$	Turn-on delay time	I_D=25A,V_{DD}=250V, R_G=25Ω,V_{GS}=10V	-	60	-	nS
T_r	Rise time		-	122	-	nS
$T_{d(off)}$	Turn-off delay time		-	124	-	nS
T_f	Fall time		-	77	-	nS
C_{iss}	Input Capacitance	V_{GS}=0V,V_{DS}=25V f=1.0MHz	-	3086	-	pF
C_{oss}	Output Capacitance		-	290	-	pF
C_{rss}	Reverse Transfer Capacitance		-	24	-	pF
Source-Drain Diode						
V_{SD}	Diode Forward Voltage	V_{GS}=0V,I_S=1A	-	-	1	V
I_{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	88	A
I_S	Maximum Continuous Drain to Source Diode Forward Current		-	-	25	A
T_{rr}	Reverse Recovery Time	V_{GS}=0V,I_F=25A, diF/dt=100A /μs	-	524	-	ns
Q_{rr}	Reverse Recovery Charge		-	9.6	-	uC

Notes:
1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. L=60mH, I_{AS}=7A, V_{DD}=150V, R_G=25Ω, Starting T_J=25°C.
3. Pulse Test: Pulse width ≤ 300μs, Duty Cycle ≤ 2% .
4. I_{SD}≤11A, di/dt≤200A/μ s, V_{DD}≤B_{VDSS} , Starting T_J = 25℃.

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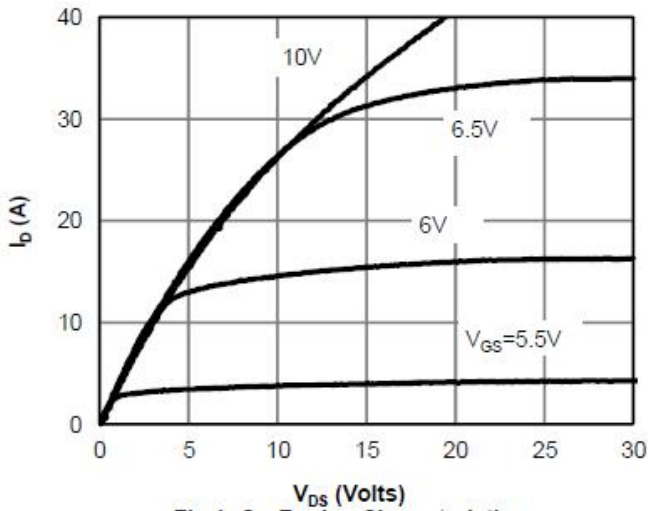
Typical Performance Characteristics
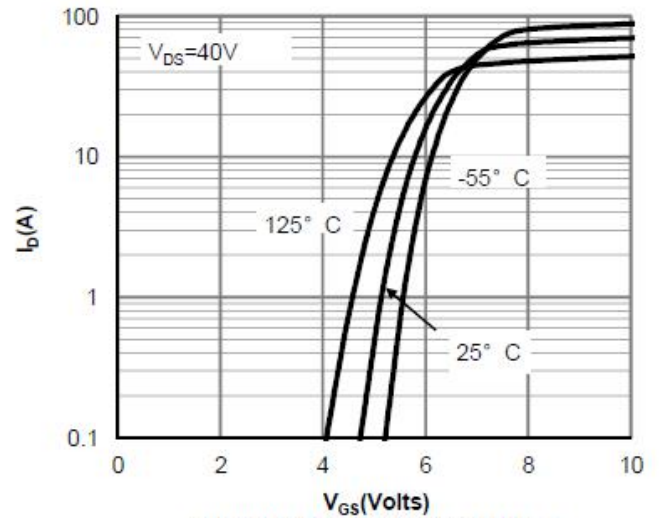

Fig 1: On-Region Characteristics
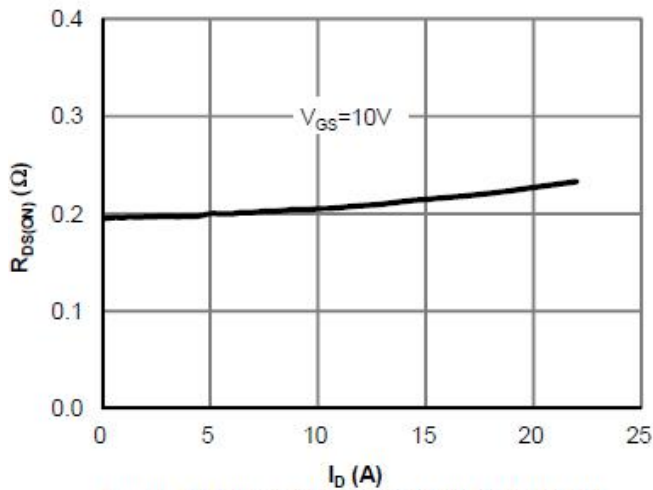

Figure 2: Transfer Characteristics

Figure 3: On-Resistance vs. Drain Current and Gate Voltage
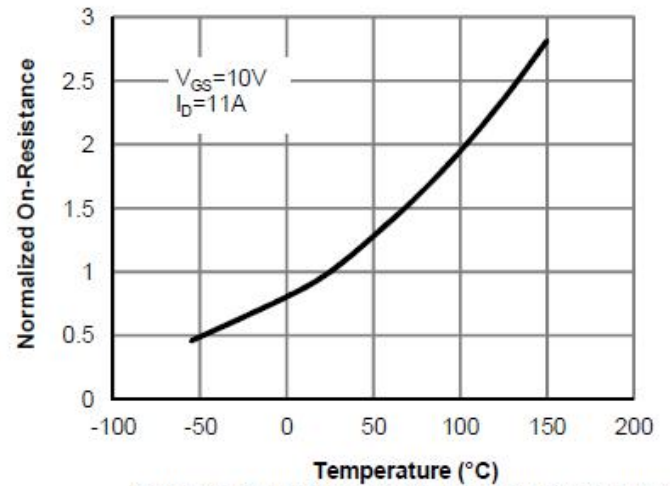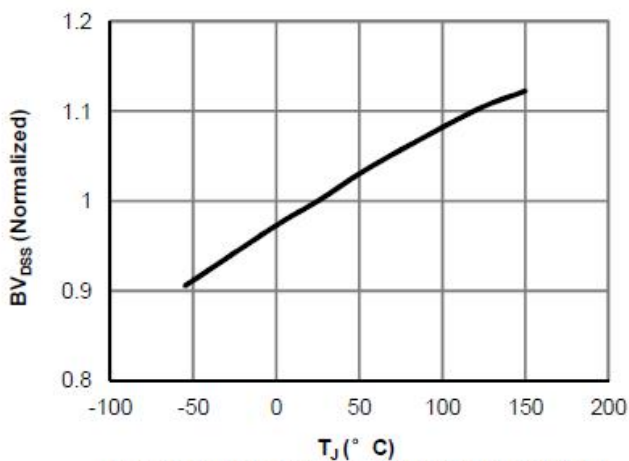

Figure 4: On-Resistance vs. Junction Temperature

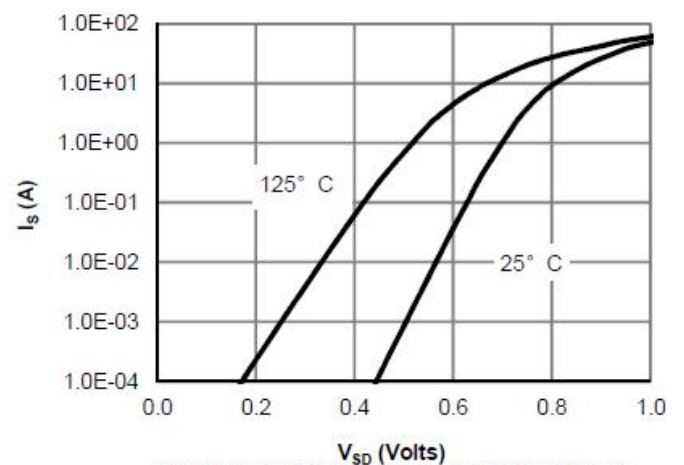Figure 5: Break Down vs. Junction Temperature

Figure 6: Body-Diode Characteristics (Note E)

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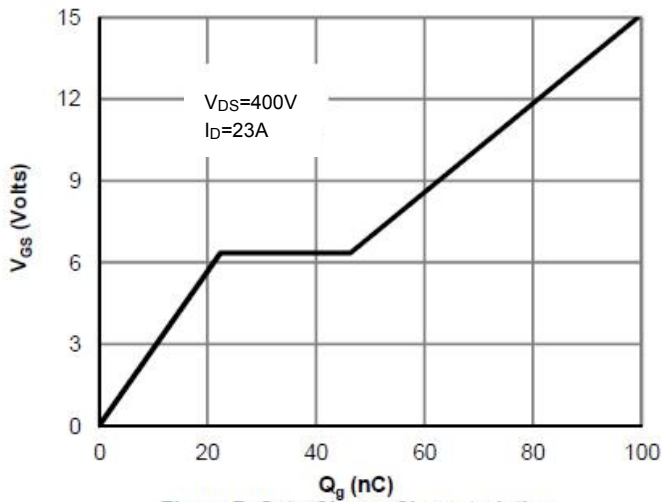## Typical Performance Characteristics (Cont.)
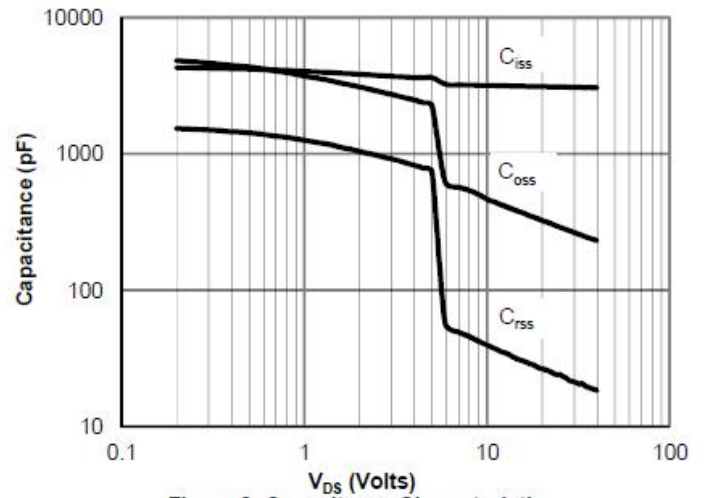

Figure 7: Gate-Charge Characteristics

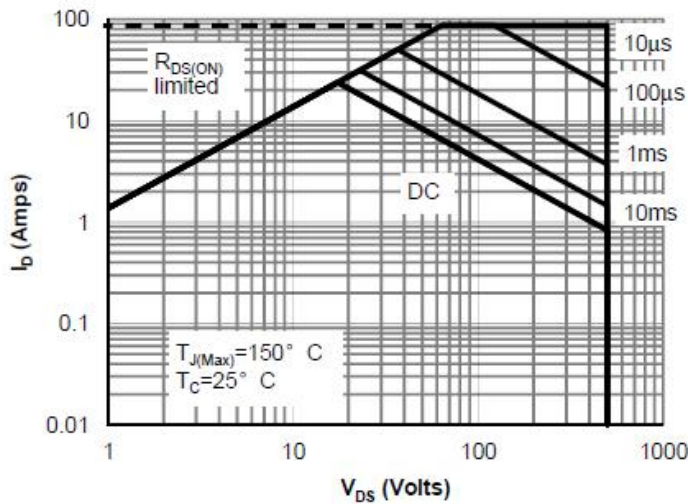Figure 8: Capacitance Characteristics

Figure 9: Maximum Forward Biased Safe Operating Area for AOT22N50 (Note F)
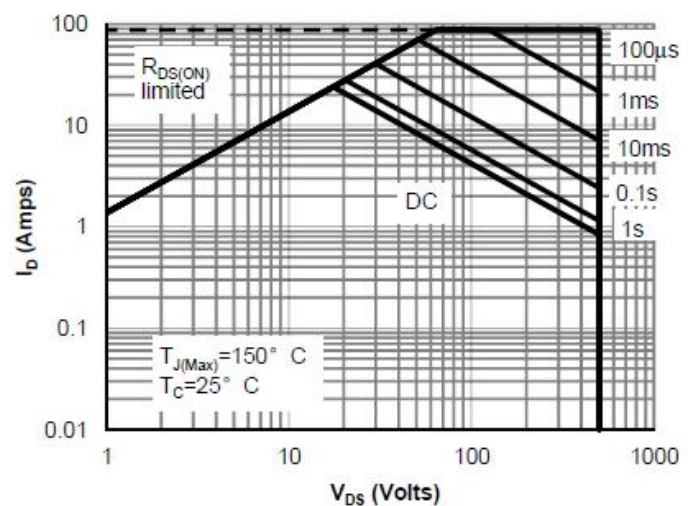

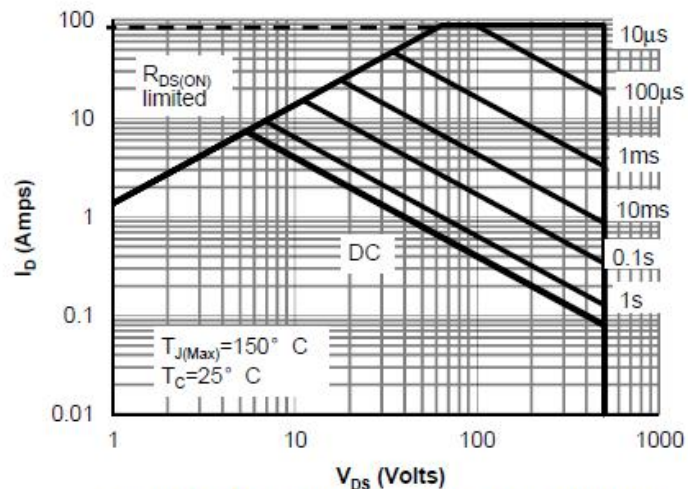Figure 10: Maximum Forward Biased Safe Operating Area for AOTF22N50 (Note F)

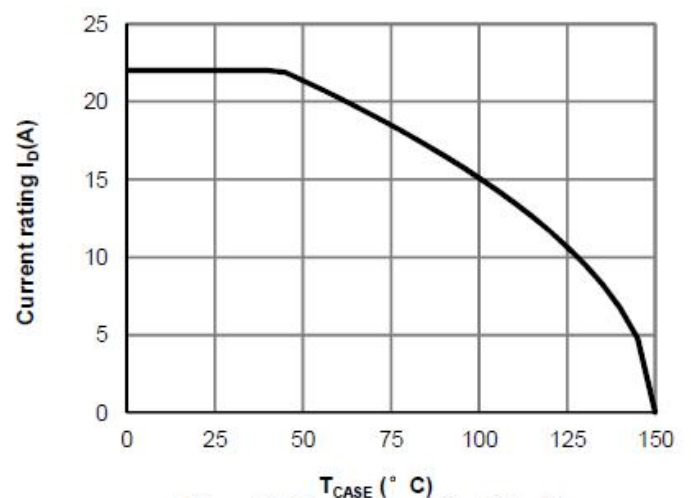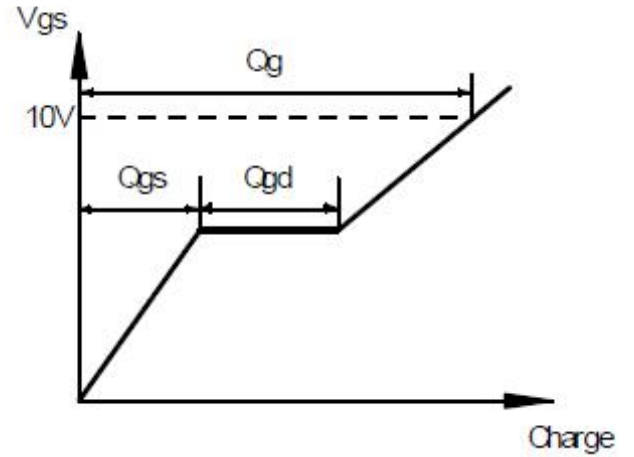Figure 12: Maximum Forward Biased Safe Operating Area for AOTF22N50L (Note F)
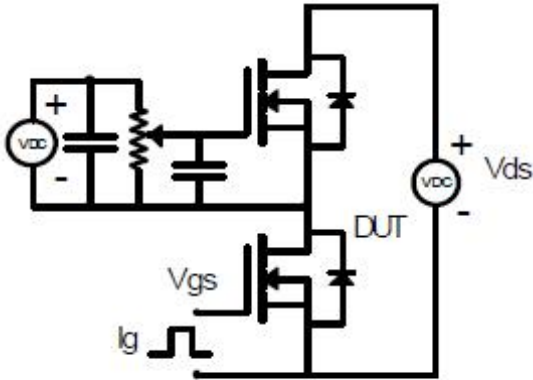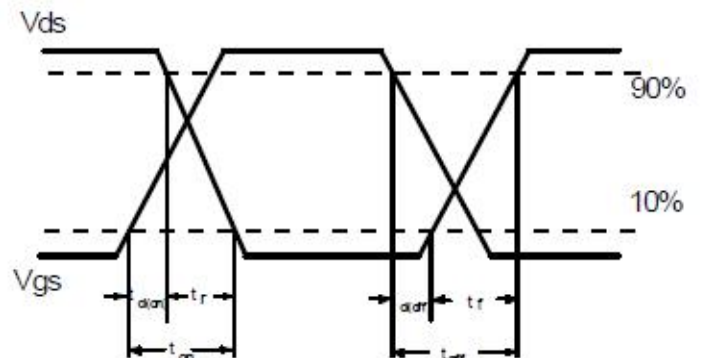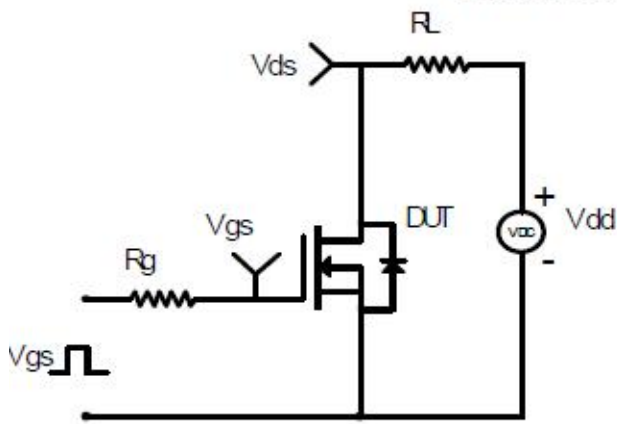

Figure 11: Current De-rating (Note B)

4

Switching Time Test Circuit and Wave forms

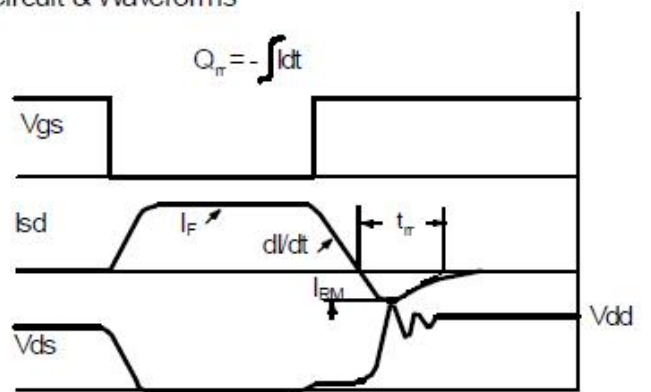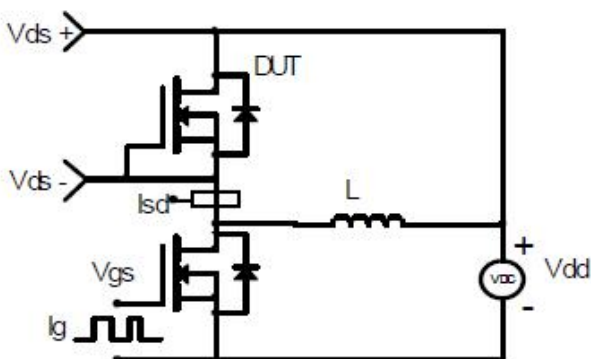### Gate Charge Test Circuit & Waveform
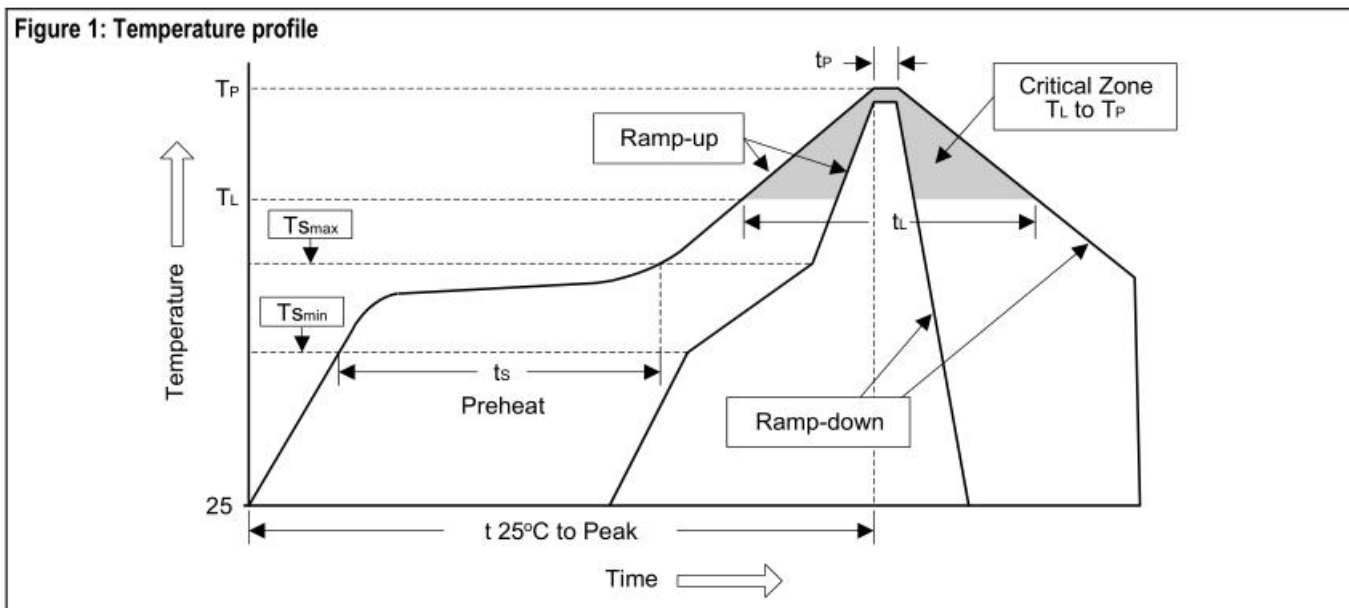
Resistive Switching Test Circuit & Waveforms

Diode Recovery Test Circuit & Waveforms

$$Q_{rr} = -\int I dt$$

■ Soldering Methods for Products

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Average ramp-up rate(TL to TP)	<3℃/sec	<3℃/sec
Preheat -Temperature Min(Ts min) -Temperature Max(Ts max) -Time(min to max)(ts)	- 100℃ 150℃ 60 to 120 sec	- 150℃ 200℃ 60 to 180 sec
Ts max to TL - ramp-up rate	<3℃/sec	<3℃/sec
Time maintained above: -Temperature(TL) -Time(TL)	183℃ 60 to 150 sec	217℃ 60 to 150 sec
Peak Temperature(TP)	240℃+0/-5℃	250℃+0/-5℃
Time within 5℃ of actual Peak Temperature	10 to 30 sec	20 to 40 sec
Ramp-down Rate	<6℃/sec	<6℃/sec
Time 25 ℃ to Peak Temperature	<6 minutes	<8 minutes

Figure 1: Temperature profile

Note : 1.Storage environment: Temperature=10℃ to 35@Humidity=45%±15%

2.Reflow soldering of surface-mount devices

3.Flow(wave) soldering(solder dipping)

Products	Peak Temperature	Dipping Time
Pb devices	245℃±5℃	5sec±1sec
Pb-free devices	250℃+0/-5℃	5sec±1sec

Package Outline

unit：mm					
Symbol	**Min**	**Max**	**Symbol**	**Min**	**Max**
A	4.80	5.20	E	15.60	16.0
A1	2.21	2.61	E1	13.3Typ.	
A2	1.90	2.10	E2	5.0Typ.	
b	1.10	1.35	E3	2.50Typ	
b1	2.0Typ		e	5.44Typ.	
b2	3.0Typ		P	3.50	3.70
C	0.55	0.75	P1	-	7.40
D	20.80	21.20	L	19.42	20.42
D1	16.55Typ.		L1	4.13Typ.	
D2	1.2Typ		S	6.05	6.25

◼ Important Notice

Si-Trend reserves the right to change all product、product specifications and data without prior notice；Our customer Please confirm to place an order confirmation before make the integrity of information complete and up-to-date。

Any semiconductor under specific conditions are possible to certain failure or malfunction rate；Customers are responsible in the use of Si-Trend products to system design and manufacturing in compliance with safety standards and adopting safety measures，To avoid the potential risk of failure may cause the personal safety and property loss。

Si-Trend Always refine on to provide more excellent products

◼ Modify record

Date	Version	Description	Pagination
20170418	A.0	original	8

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